

May 2009

FDS4141_F085

P-Channel PowerTrench $^{\circledR}$ MOSFET -40V, -10.8A, 19.0m Ω

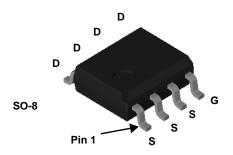
Features

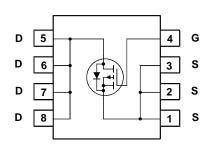
- Typ $r_{DS(on)} = 10.5 m\Omega$ at $V_{GS} = -10 V$, $I_D = -10.5 A$
- Typ $r_{DS(on)} = 14.8 \text{m}\Omega$ at $V_{GS} = -4.5 \text{V}$, $I_D = -8.4 \text{A}$
- Typ $Q_{q(TOT)} = 35nC$ at $V_{GS} = -10V$
- \blacksquare High performance trench technology for extremely low $r_{\mathsf{DS}(\mathsf{on})}$
- RoHS Compliant
- Qualified to AEC Q101

Applications

- Control switch in synchronous & non-synchronous buck
- Load switch
- Inverter







Units

Max

MOSFET Maximum Ratings $T_A = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Ratings	Units
V _{DSS}	Drain to Source Voltage	-40	V
V _{GS}	Gate to Source Voltage	±20	V
-	Drain Current Continuous (V _{GS} = 10V)	-10.8	Δ.
Pulsed		-36	A
E _{AS} Single Pulse Avalanche Energy		229	mJ
P_D	Power Dissipation 1.6		W
T_J , T_{STG}	Operating and Storage Temperature	-55 to +150	οС

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance Junction to Case	30	°C/W
$R_{\theta JA}$	Thermal Resistance Junction to Ambient SO-8, 1in ² copper pad area	81	°C/W

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDS4141	FDS4141_F085	SO-8	13"	12mm	2500 units

Electrical Characteristics T_A = 25°C unless otherwise noted

Parameter

Off Ch	aracteristics					
B_{VDSS}	Drain to Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -32V,	-	-	-1	μΑ
I _{GSS}	Gate to Source Leakage Current	$V_{GS} = \pm 20V$	-	-	±100	nA

Test Conditions

Min

Тур

On Characteristics

Symbol

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = -250 \mu A$	-1.0	-1.7	-3.0	V
Prain to Source On Resistance	$I_D = -10.5A, V_{GS} = -10V$	-	10.5	13.0		
	$I_D = -8.4A, V_{GS} = -4.5V$	-	14.8	19.0	mΩ	
r _{DS(on)}	Drain to Source Of Nesistance	$I_D = -10.5A, V_{GS} = -10V,$ $T_J = 125^{\circ}C$	-	15.3	19.0	11152
9 _{FS}	Forward Transconductance	$I_D = -10.5A, V_{DD} = -5V$		34		S

Dynamic Characteristics

C _{iss}	Input Capacitance	V 00V V	$V_{DS} = -20V, V_{GS} = 0V,$		2005	-	pF
C _{oss}	Output Capacitance	$V_{DS} = -20V, V_{GS} =$ $= 1MHz$			355	-	pF
C _{rss}	Reverse Transfer Capacitance	1 – 1101112	1 = 1WHZ		190	-	pF
R_{g}	Gate Resistance	f = 1MHz	f = 1MHz		5.0	-	Ω
$Q_{g(TOT)}$	Total Gate Charge at -10V	$V_{GS} = 0 \text{ to } -10V$	V _{GS} = 0 to -10V		35	45	nC
Q _{g(-5)}	Total Gate Charge at -5V	$V_{GS} = 0 \text{ to } -5V$	$V_{GS} = 0 \text{ to -5V}$ $V_{DD} = -20V$		18.6	24.2	nC
Q_{gs}	Gate to Source Gate Charge		I _D = -10.5A		5.2	-	nC
Q_{gd}	Gate to Drain "Miller" Charge			-	6.6	-	nC

Electrical Characteristics $T_A = 25^{o}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Switch	ing Characteristics					

t _{on}	Turn-On Time		-	-	25	ns
t _{d(on)}	Turn-On Delay Time	Ī.,	-	9.7	-	ns
t _r	Rise Time	$V_{DD} = -20V, I_D = -10.5A$	-	4.4	-	ns
t _{d(off)}	Turn-Off Delay Time	$V_{GS} = -10V, R_{GEN} = 6\Omega$	-	41	-	ns
t _f	Fall Time		-	11.6	-	ns
t _{off}	Turn-Off Time		-	-	84	ns

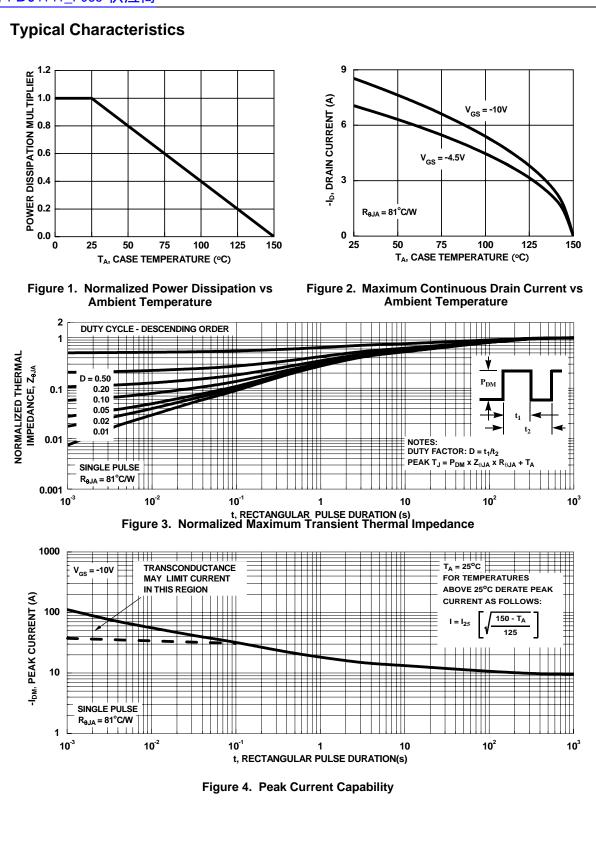
Drain-Source Diode Characteristics

Ved Source to Drain Diode Voltage	Source to Drain Diode Voltage	I _{SD} = -10.5A	-	-0.8	-1.3	V
	I _{SD} = -2.1A		-0.7	-1.2	V	
t _{rr}	Reverse Recovery Time	1 10 FA d /dt 100 A /	-	26	34	ns
Q _{rr}	Reverse Recovery Charge	$I_F = -10.5A$, $d_{SD}/dt = 100A/\mu s$ - 13		13.4	17.4	nC

Notes:

1: Starting $T_J = 25^{\circ}C$, L = 6.2mH, $I_{AS} = -8.6A$

This product has been designed to meet the extreme test conditions and environment demanded by the automotive industry. For a copy of the requirements, see AEC Q101 at: http://www.aecouncil.com/
All Fairchild Semiconductor products are manufactured, assembled and tested under ISO9000 and QS9000 quality systems certification.



Typical Characteristics

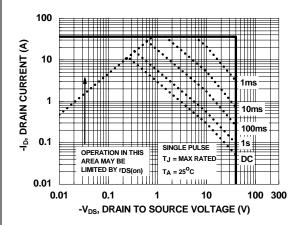
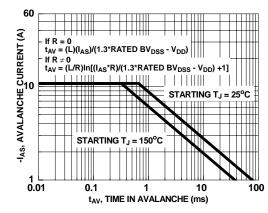


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching Capability

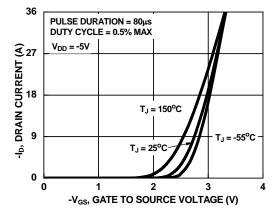


Figure 7. Transfer Characteristics

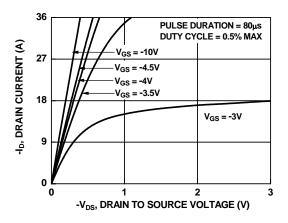


Figure 8. Saturation Characteristics

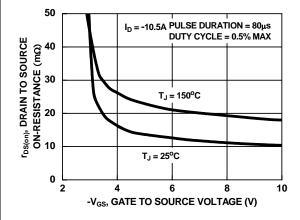


Figure 9. Drain to Source On-Resistance Variation vs Gate to Source Voltage

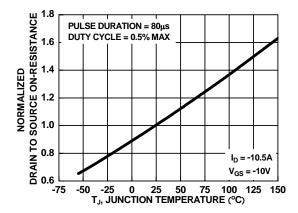


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics

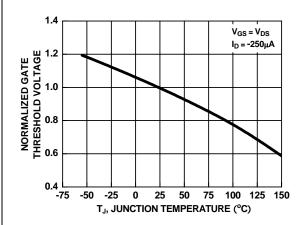


Figure 11. Normalized Gate Threshold Voltage vs
Junction Temperature

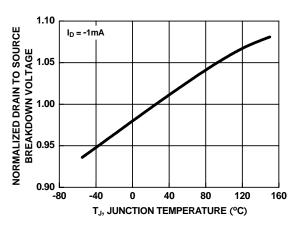


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

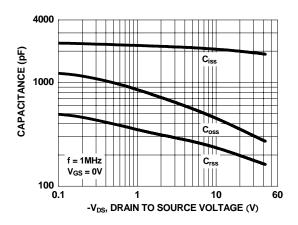


Figure 13. Capacitance vs Drain to Source Voltage

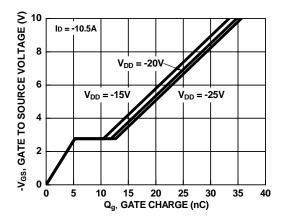


Figure 14. Gate Charge vs Gate to Source Voltage

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